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Journal of Electronic Packaging

Guest Editorial

Special Issue on InterPACK2020

The microelectronics packaging industry is facing challenges to meet demanding performance and functional needs of modern microprocessors, radio frequency components, and power electronic devices for various product segments including personal computers, data centers, mobile devices, power converters, and automotive electronics. To realize the new era of big data, the semiconductor industry has launched new technologies, including heterogeneous integration, 2.5D/3D electronic packaging, chiplet, additive manufacturing, novel modeling and characterization techniques, and others. InterPACK is a premier international forum for the exchange of state-of-the-art knowledge in research, development, and applications of electronic and photonic packaging. It is the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). This Special Issue of the ASME *Journal of Electronic Packaging* (JEP) publishes papers presented at the InterPACK2020 conference to disseminate latest advancements in the areas of electronics and photonics packaging, device to package level thermal management, and others. All papers published in this JEP Special Issue for InterPACK2020 have gone through a peer-review process in accordance with the editorial procedures of JEP.

The aim of this JEP InterPACK Special Issue is to publish outstanding papers from the following tracks of InterPACK2020: heterogeneous integration, servers of the future, edge and cloud computing, flexible and wearable electronics, optics and photonics, power electronics, multiscale energy transport, conversion and storage, autonomous, hybrid, and electric vehicles. This collection of papers will be an excellent resource for the readers and subscribers of the ASME JEP. We gratefully acknowledge all the authors whose work appear in this Special Issue and the reviewers for their help in improving the quality of these papers. We would also like to acknowledge the ASME JEP Editor-in-Chief, Professor Shi-Wei Ricky Lee, for his support.

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